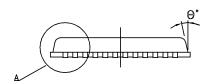
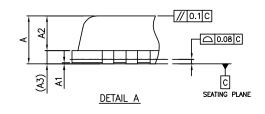


TOP VIEW



EXPOSED THERMAL PAD	D2	
υ T	15 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0	Ī
Ţ		
	K	ļ
<u>L</u>	48 b h - =	
	BOTTOM VIEW	



SYMBOLS	MIN.	MIN. NOM.					
Α	0.80	0.90	1.00				
A1	0.00	0.00 0.02					
A2	0.65 REF.						
A3	0.203 REF.						
b	0.18	0.25	0.30				
h	0.24	0.42	0.60				
D	6.90	7.00	7.10				
D1	6.65	6.75	6.85				
Ε	6.90	7.00	7.10				
E1	6.65	6.65 6.75					
е	0.50 BSC.						
K	0.20	_	_				
L	0.30	0.40	0.50				
θ,	0.00	_	12.00				

UNIT : mm

	D2			E2		
PAD SIZE	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
157X157MIL	3.40	3.60	3.80	3.40	3.60	3.80
213X213MIL	5.00	5.20	5.40	5.00	5.20	5.40
208X208MIL	4.90	5.10	5.30	4.90	5.10	5.30

UNIT: mm

PERICON Semiconductor Corporation

DATE: 03/09/12

1. All dimensions are in millimeters, angles are in degrees.

Coplanarity applies to the exposed thermal pad as well as the terminals.
Refer JEDEC MO-220

DESCRIPTION: 48-Pin, Thin Fine Pitch Quad Flat No-Lead (TQFN)

PACKAGE CODE: ZB48

DOCUMENT CONTROL #: PD-2080

REVISION: B